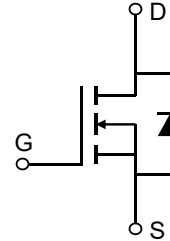


### Description

#### Features

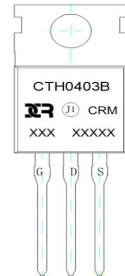
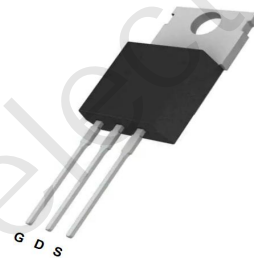
- 40V, 168A  
 $R_{DS(ON)} \text{ Typ} = 2.5\text{m}\Omega @ V_{GS} = 10\text{V}$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE (pcs)	Inner Box (pcs)	Per Carton (pcs)
CRMCTH0403B	CRMCTH0403B	TO-220C-3L	TUBE	50	1000	5000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	40	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	168
		$T_C = 100^\circ\text{C}$	100
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	672	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	462	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	156
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.8	$^\circ\text{C/W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

### Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
--------	-----------	------------	------	------	------	------

#### Off Characteristics

V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.5	3.0	3.5	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	2.5	3.3	mΩ

#### Dynamic Characteristics

C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 20V, f = 1MHz	-	7960	-	pF
C <sub>oss</sub>	Output Capacitance		-	681	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	489	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 20V, I <sub>D</sub> = 20A	-	140	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	28	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	36	-	nC

#### Switching Characteristics

t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 20V I <sub>D</sub> = 20A, R <sub>GEN</sub> = 3Ω	-	35	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	38	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	110	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	60	-	ns

#### Drain-Source Diode Characteristics and Max Ratings

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	168	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	672	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage		-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time		-	50	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	75	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=20V, V<sub>G</sub>=10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=43A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

## Typical Performance Characteristics

Figure 1: Output Characteristics

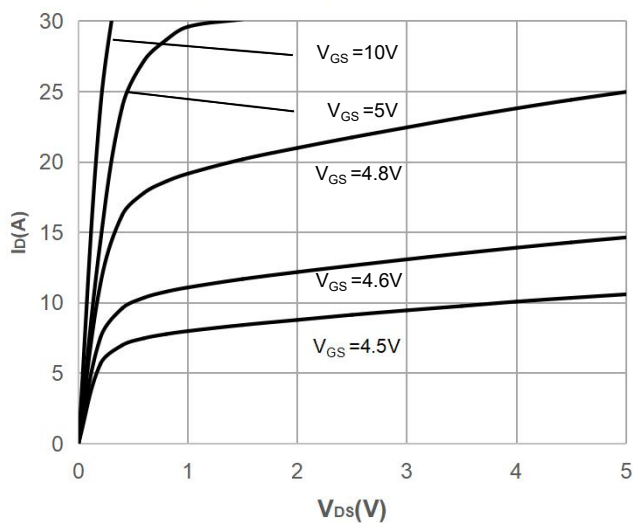


Figure 2: Typical Transfer Characteristics

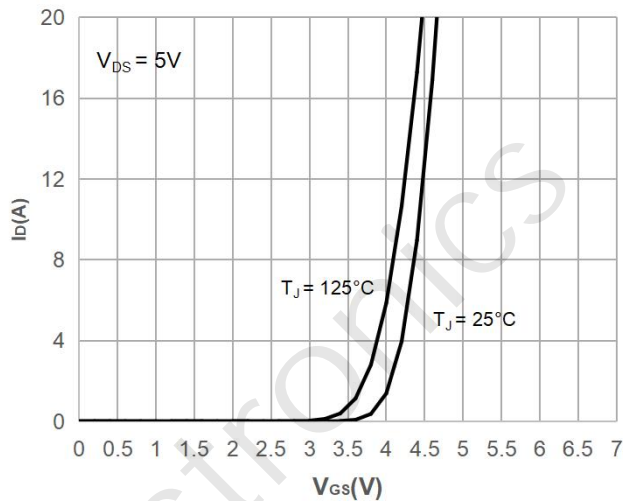


Figure 3: On-resistance vs. Drain Current

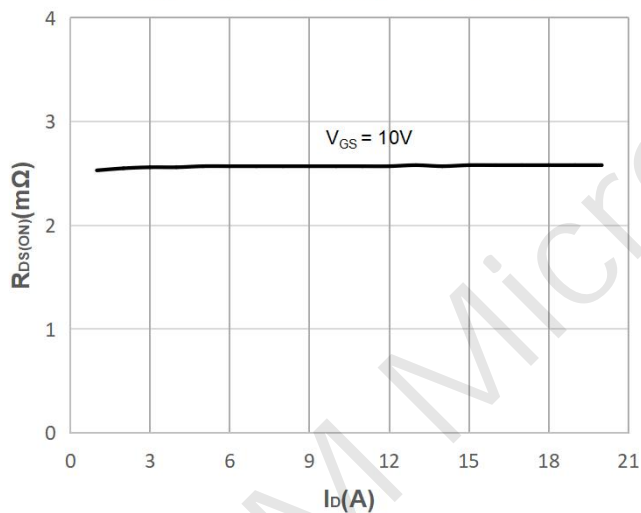


Figure 4: Body Diode Characteristics

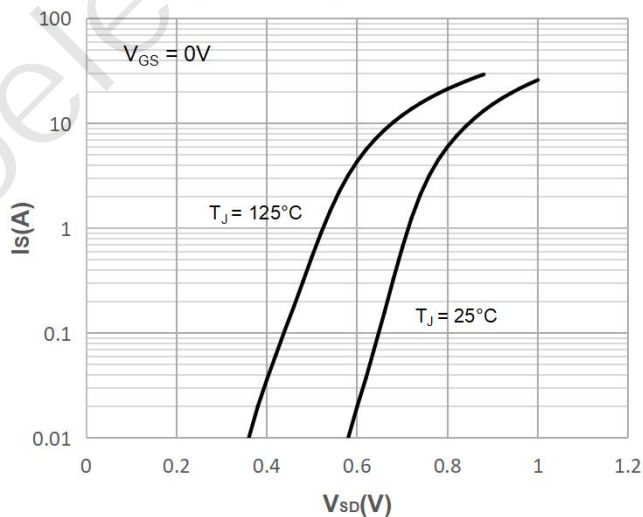


Figure 5: Gate Charge Characteristics

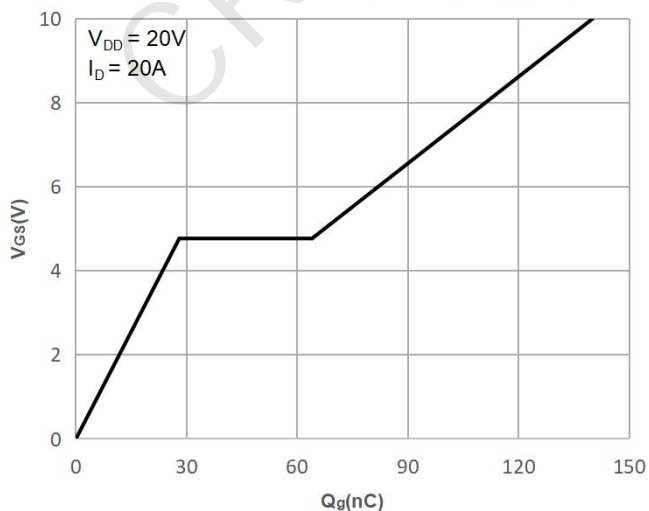
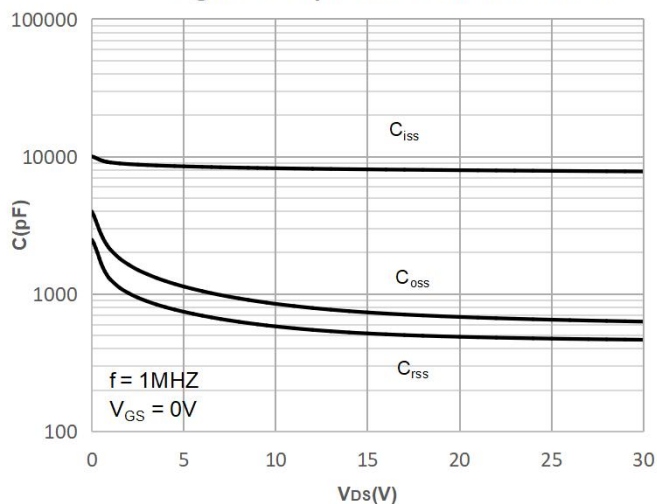


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

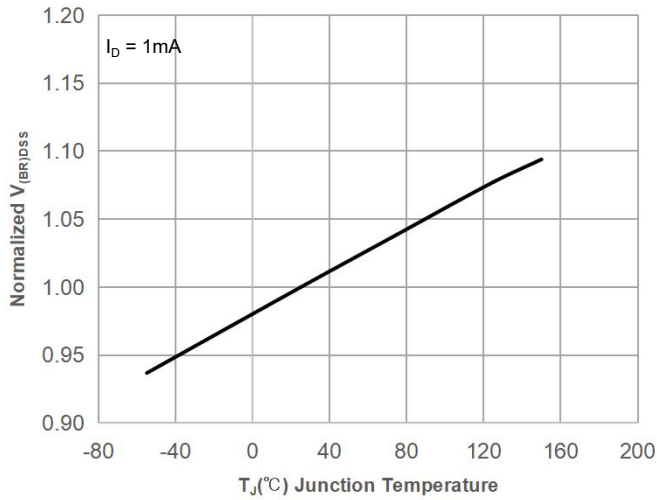


Figure 8: Normalized on Resistance vs. Junction Temperature

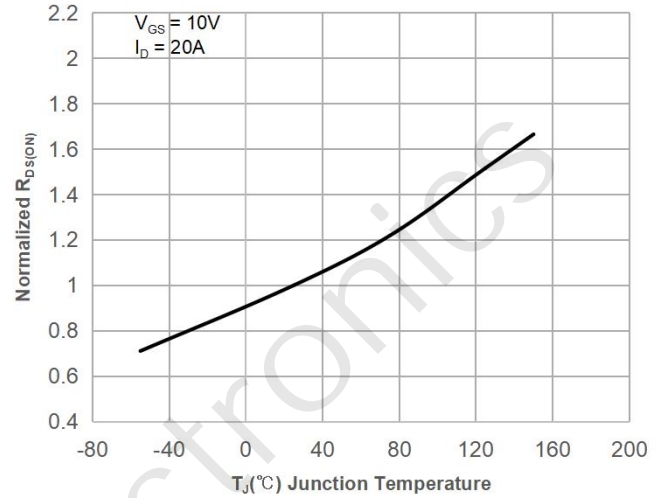


Figure 9: Maximum Safe Operating Area

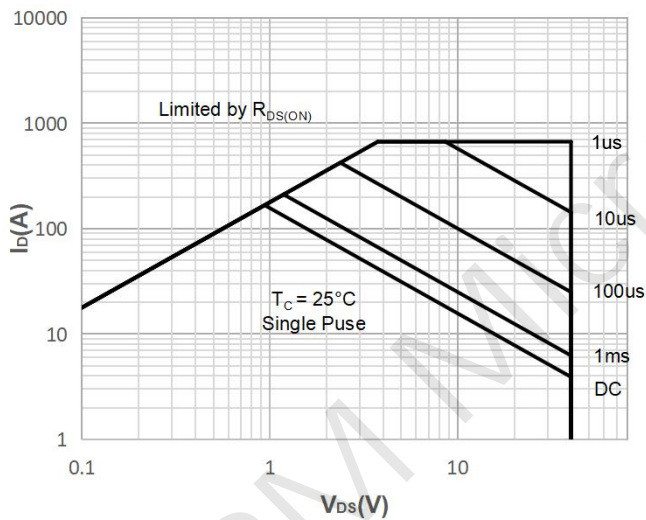


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

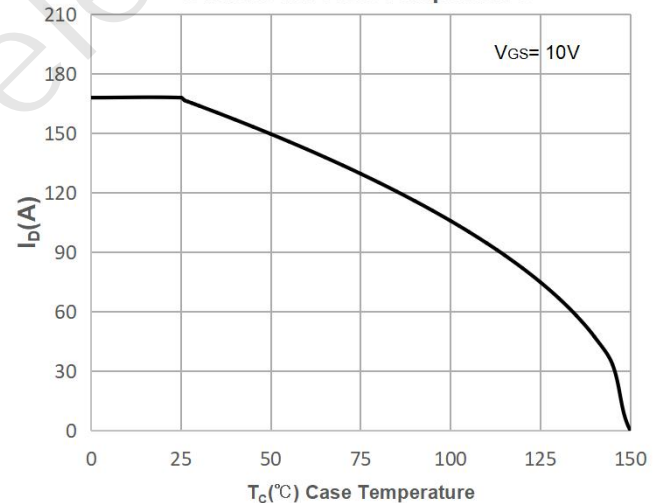


Figure 11: Normalized Maximum Transient Thermal Impedance

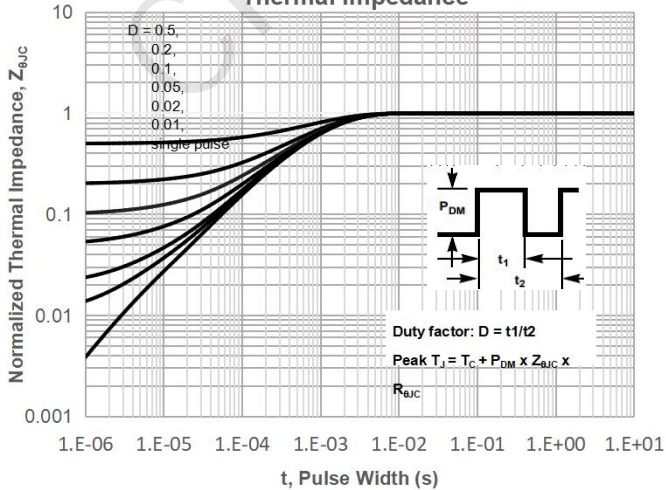
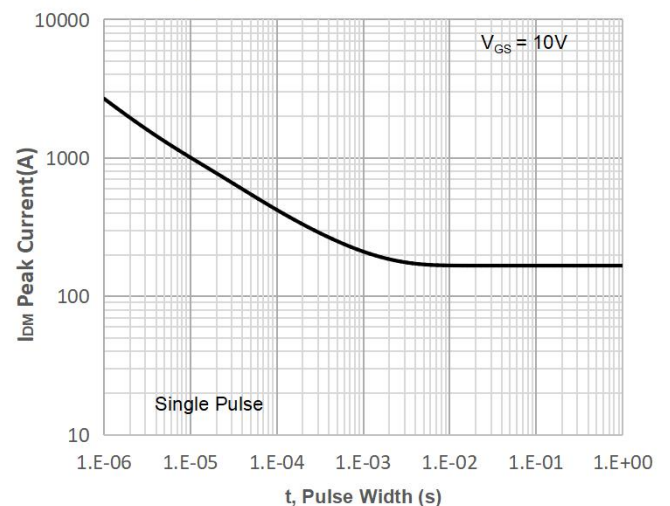


Figure 12: Peak Current Capacity



## Test Circuit

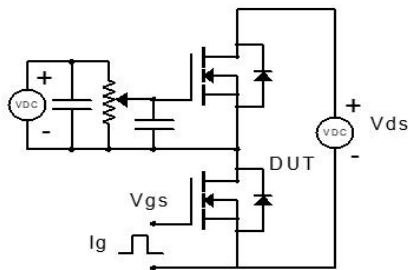


Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

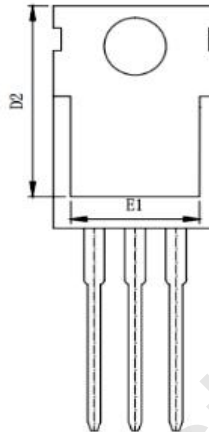
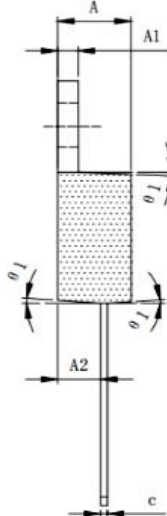
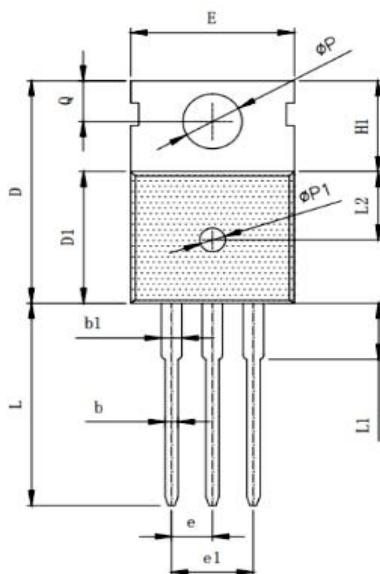


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

## Package Mechanical Data(TO-220C-3L)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	1.25	1.30	1.35
A2	2.30	2.40	2.50
b	0.70	0.80	0.90
b1	1.25	1.35	1.45
c	0.40	0.50	0.60
D	15.50	15.80	16.10
D1	9.10	9.20	9.30
D2	12.73	12.83	12.93
E	9.70	9.90	10.20
E1	7.60	8.00	8.40
e	2.54 (BSC)		
e1	5.08 (BSC)		
H1	6.30	6.50	6.80
L	12.75	13.08	13.50
L1	--	--	3.10
L2	4.30	4.60	4.90
φP	3.50	3.60	3.70
φP1	1.40	1.50	1.60
Q	2.70	--	2.90
θ1	2°	4°	6°

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